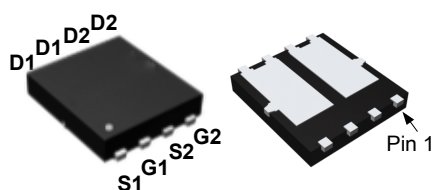


Dual Enhancement Mode MOSFET (N-and P-Channel)

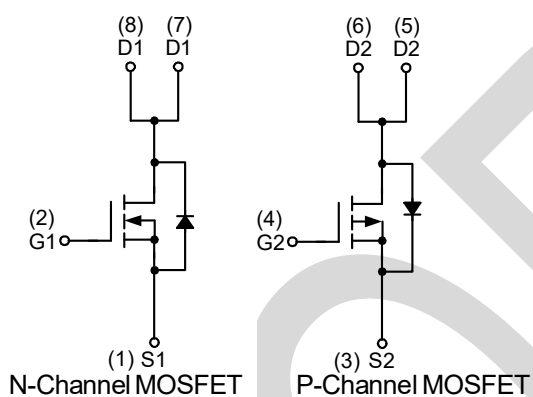
MSR013X03SD2

PDFN5x6



N-channel	V_{DS}	30	V
	$R_{DS(on),TYP@ V_{GS}=10\text{ V}}$	10	mΩ
	$R_{DS(on),TYP@ V_{GS}=4.5\text{ V}}$	17	mΩ
	I_D	15	A

P-channel	V_{DS}	-30	V
	$R_{DS(on),TYP@ V_{GS}= -10\text{ V}}$	25	mΩ
	$R_{DS(on),TYP@ V_{GS}= -4.5\text{ V}}$	34	mΩ
	I_D	-15	A



Features

- 1、Reliable and Rugged
- 2、High power package (PDFN5X6)
- 3、Lead Free Available (RoHS Compliant)

Applications

- 1、Synchronous Rectification.
- 2、Motor Control.
- 3、High Current, High Speed Switching.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		N Channel	P Channel	Unit
Common Ratings					
V _{DSS}	Drain-Source Voltage		30	-30	V
V _{GSS}	Gate-Source Voltage		±20	±25	
T _J	Maximum Junction Temperature		150		°C
T _{STG}	Storage Temperature Range		-55 to 150		
I _S	Diode Continuous Forward Current	T _C =25°C	15	-15	A
I _D	Continuous Drain Current(Wire Bond Limited)	T _C =25°C	15	-15	A
		T _C =100°C	6	-6	
P _D	Maximum Power Dissipation	T _C =25°C	19	19	W
		T _C =100°C	7.7	7.7	
R _{θJC}	Thermal Resistance-Junction to Case	Steady State	6.5	6.5	°C/W
I _D	Continuous Drain Current	T _A =25°C	9.3	-6.8	A
		T _A =70°C	7.4	-5.4	
I _{DM} ^a	Pulsed Drain Current	T _A =25°C	37	-28	A
P _D	Maximum Power Dissipation	T _A =25°C	1.42	1.42	W
		T _A =70°C	0.9	0.9	
R _{θJA} ^b	Thermal Resistance-Junction to Ambient	t ≤ 10s	45	45	°C/W
		Steady State	88	88	°C/W
I _{AS} ^c	Avalanche Current, Single pulse	L=0.1mH	23	-24	A
E _{AS} ^c	Avalanche Energy, Single pulse	L=0.1mH	26.45	-28.8	mJ

Note a : Max. continuous current is limited by bonding wire.

Note b : Pulse width limited by max. junction temperature.

Note c : Surface Mounted on 1in^2 pad area, steady state $t = 999\text{s}$.

Note d : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^\circ\text{C}$)

N Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	N Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.5	1.8	2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =8A	-	10	13	mΩ
		T _J =125°C	-	13.9	-	
		V _{GS} =4.5V, I _{DS} =5A	-	17	19	
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =5A	-	15	-	S
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =3A, V _{GS} =0V	-	0.75	1.1	V
t _{rr}	Reverse Recovery Time	I _{SD} =8A, dI _{SD} /dt=100A/μs	-	11.7	-	ns
t _a	Charge Time		-	4.8	-	
t _b	Discharge Time		-	6.9	-	
Q _{rr}	Reverse Recovery Charge		-	1.7	-	nC
Dynamic Characteristics ^f						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	0.9	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, Frequency=1.0MHz	-	940	-	pF
C _{oss}	Output Capacitance		-	150	-	
C _{rss}	Reverse Transfer Capacitance		-	100	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =15V, R _L =15Ω, I _{DS} =1A, V _{GEN} =10V, R _G =1Ω	-	11.9	-	ns
t _r	Turn-on Rise Time		-	10.1	-	
t _{d(OFF)}	Turn-off Delay Time		-	22	-	
t _f	Turn-off Fall Time		-	5	-	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _{DS} =8A	-	8.7	-	nC
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _{DS} =8A	-	18	-	
Q _{gth}	Threshold Gate Charge		-	1.24	-	
Q _{gs}	Gate-Source Charge		-	2	-	
Q _{gd}	Gate-Drain Charge		-	4	-	

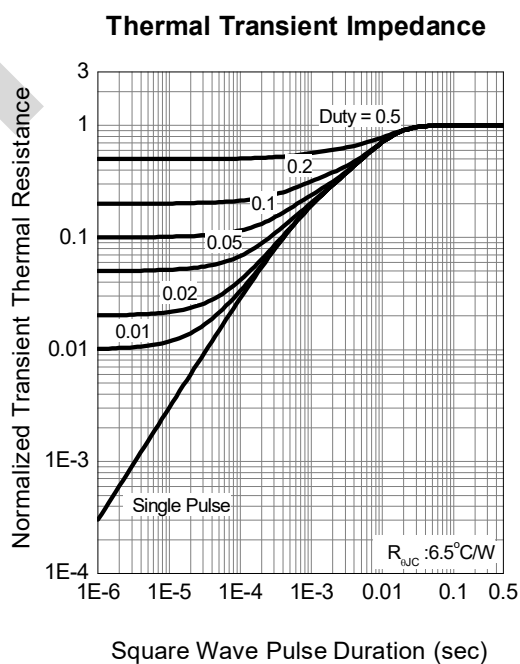
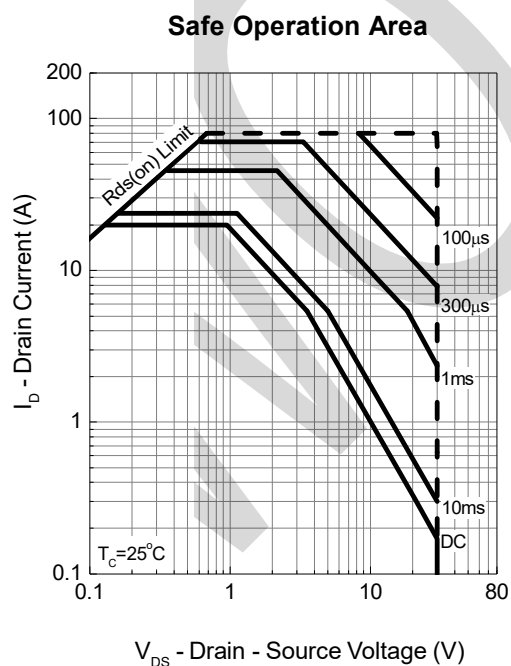
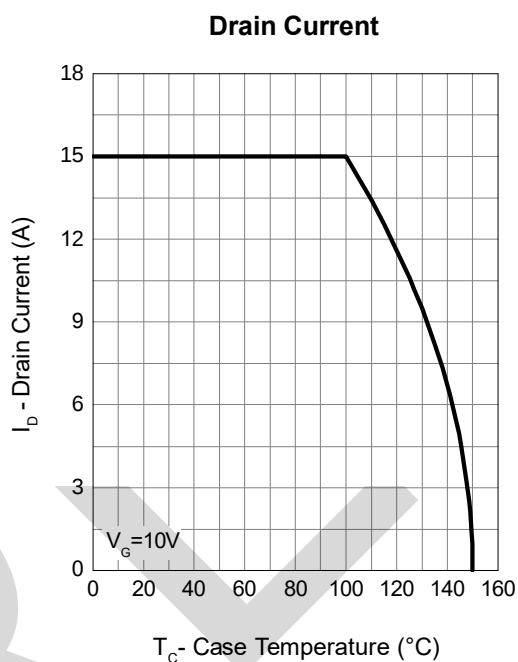
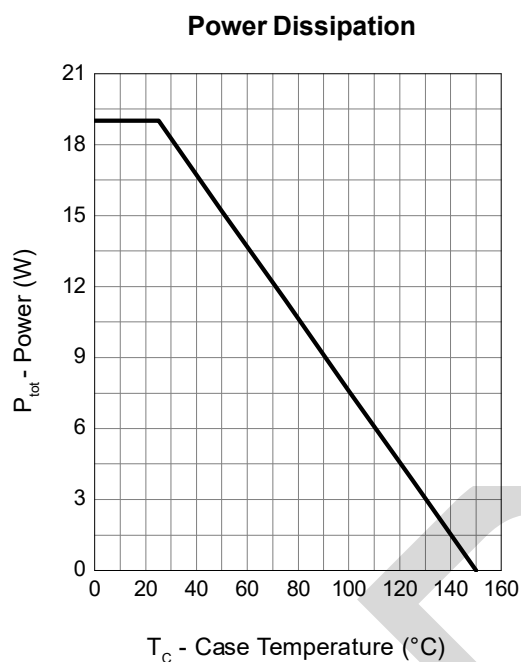
Note e : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Note f : Guaranteed by design, not subject to production testing.

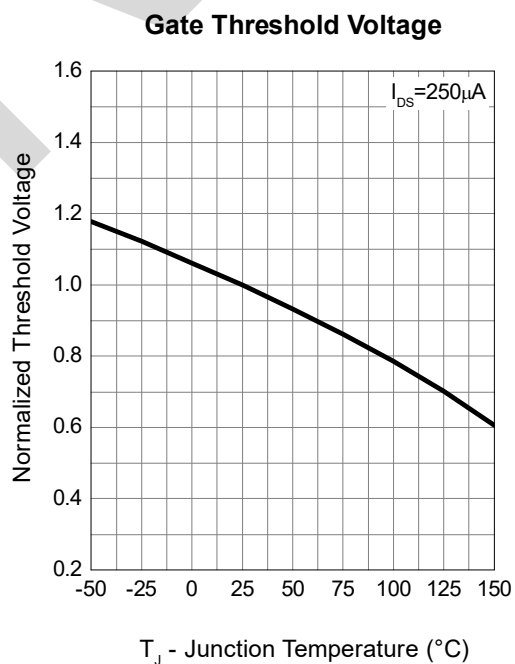
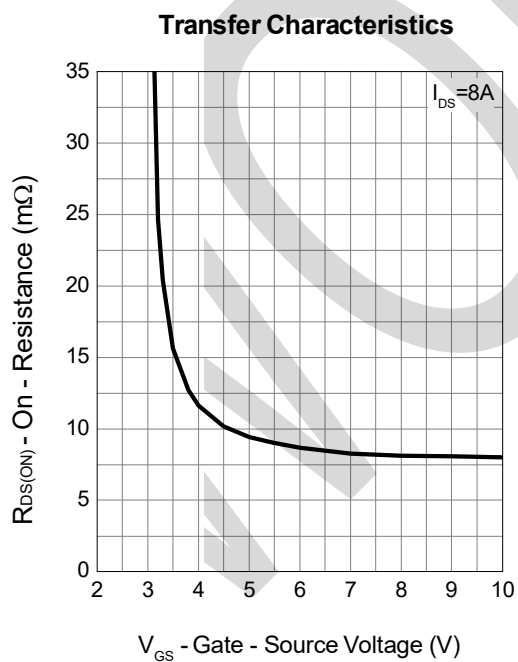
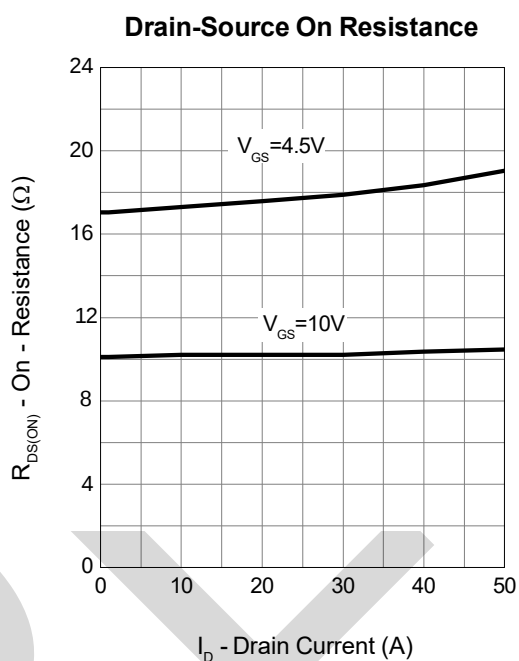
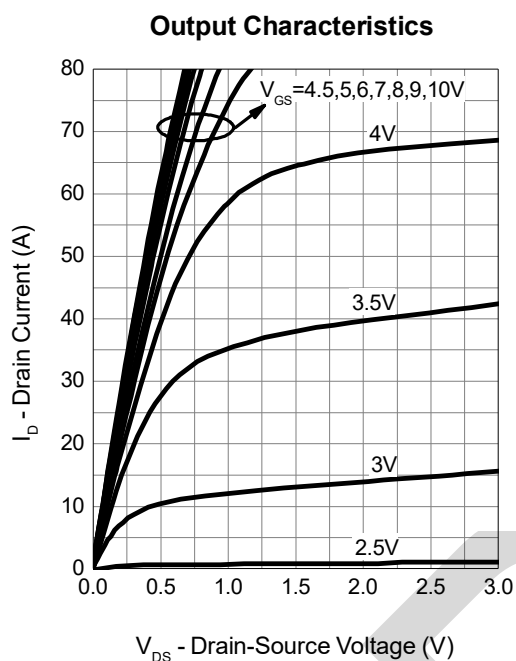
P Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	P Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-24V, V _{GS} =0V T _J =85°C	-	-	-1	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-1.5	-2	-2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} =-10V, I _{DS} =-10A T _J =125°C	-	25	28	mΩ
		V _{GS} =-4.5V, I _{DS} =-5A	-	34	40	
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =5A	-	13	-	S
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =-1A, V _{GS} =0V	-	-0.75	-1	V
t _{rr}	Reverse Recovery Time	I _{SD} =-10A, dI _{SD} /dt=100A/μs	-	26	-	ns
t _a	Charge Time		-	8	-	
t _b	Discharge Time		-	18	-	
Q _{rr}	Reverse Recovery Charge		-	7	-	nC
Dynamic Characteristics ^f						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	3.4	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, Frequency=1.0MHz	-	1000	-	pF
C _{oss}	Output Capacitance		-	210	-	
C _{rss}	Reverse Transfer Capacitance		-	150	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-15V, R _L =15Ω, I _{DS} =-1A, V _{GEN} =-10V, R _G =6Ω	-	11	-	ns
t _r	Turn-on Rise Time		-	12	-	
t _{d(OFF)}	Turn-off Delay Time		-	26	-	
t _f	Turn-off Fall Time		-	12	-	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-4.5V, I _{DS} =-10A	-	9.6	-	nC
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-10V, I _{DS} =-10A	-	21	-	
Q _{gth}	Threshold Gate Charge		-	1.5	-	
Q _{gs}	Gate-Source Charge		-	3.5	-	
Q _{gd}	Gate-Drain Charge		-	5.9	-	

N Channel Typical Operating Characteristics

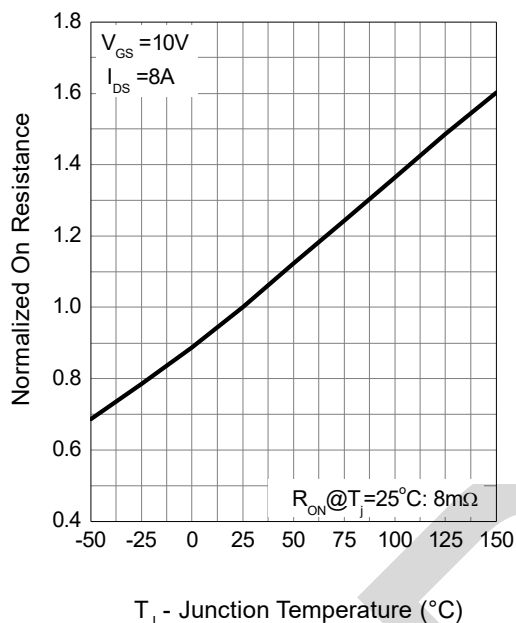


N Channel Typical Operating Characteristics (Cont.)

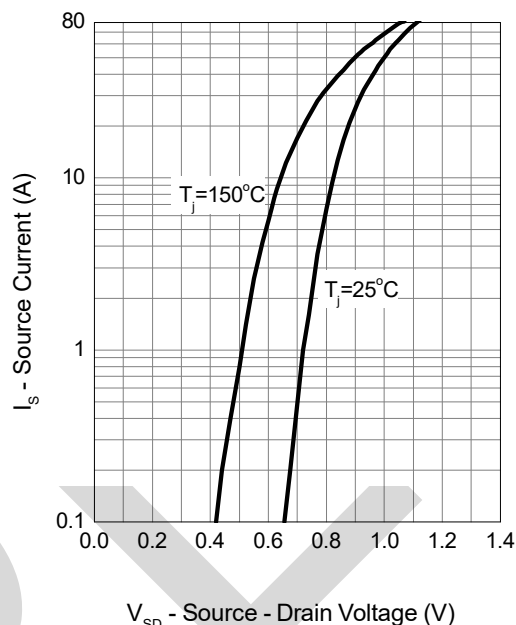


N Channel Typical Operating Characteristics (Cont.)

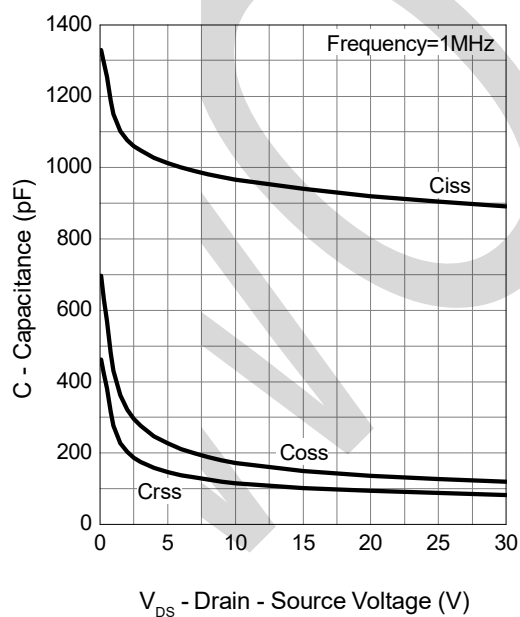
Drain-Source On Resistance



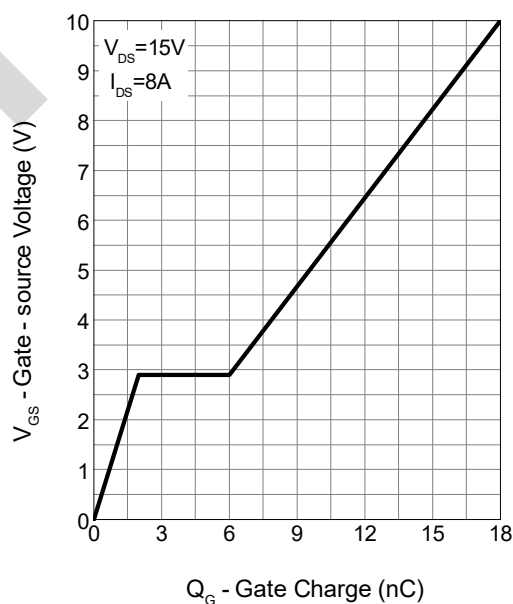
Source-Drain Diode Forward



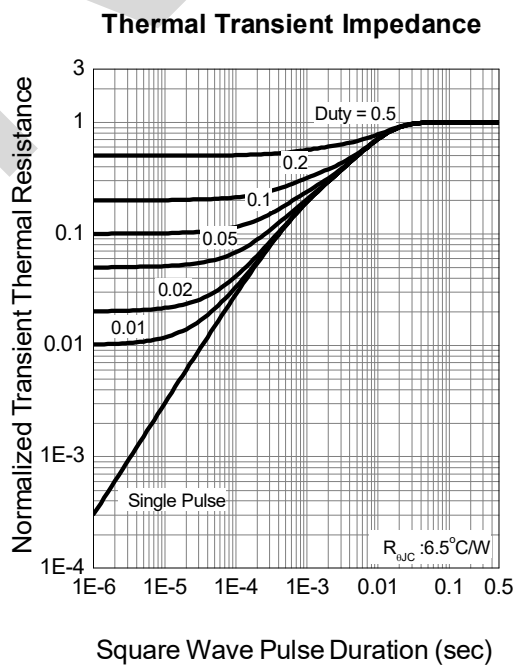
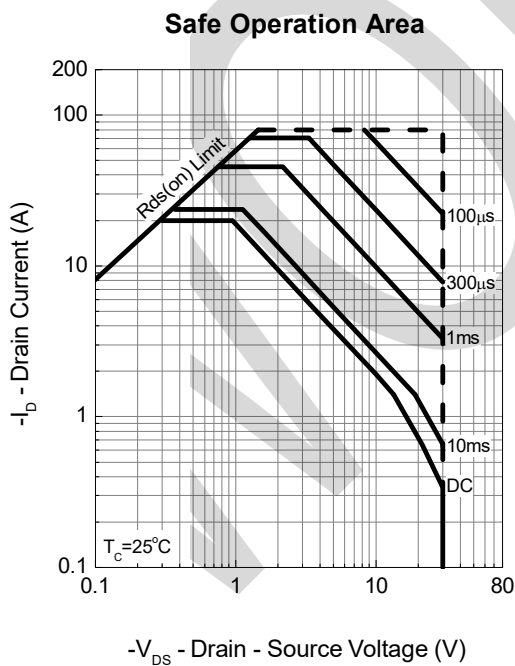
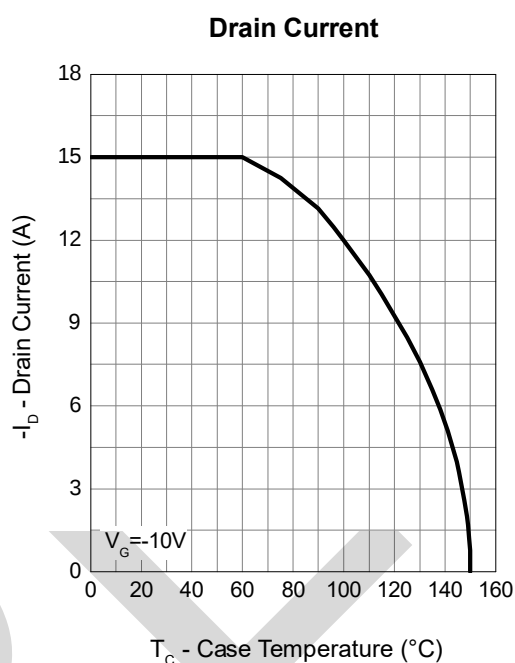
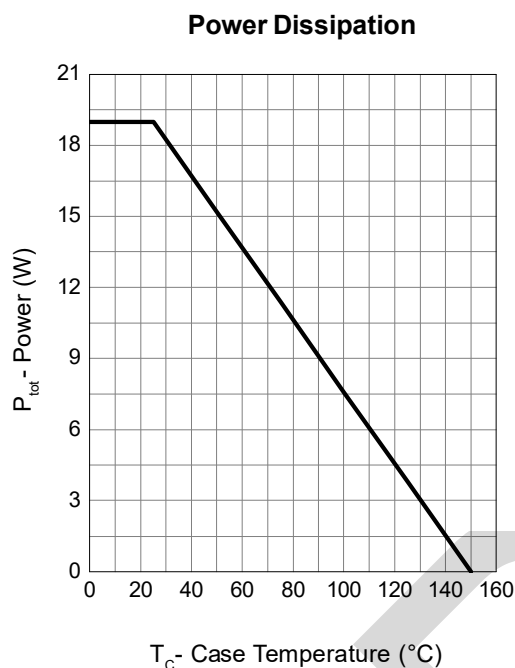
Capacitance



Gate Charge

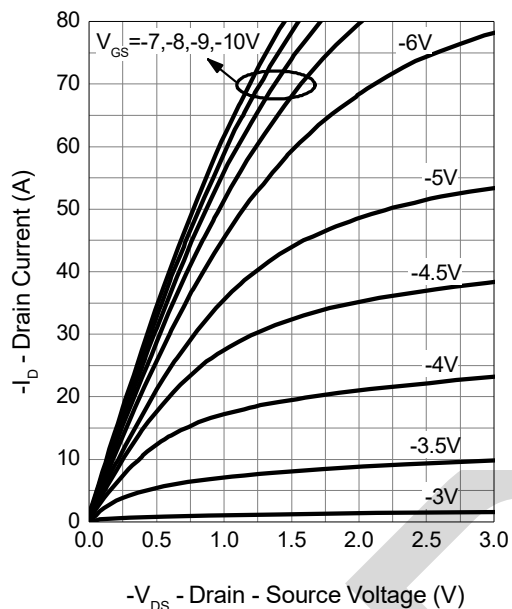


P Channel Typical Operating Characteristics

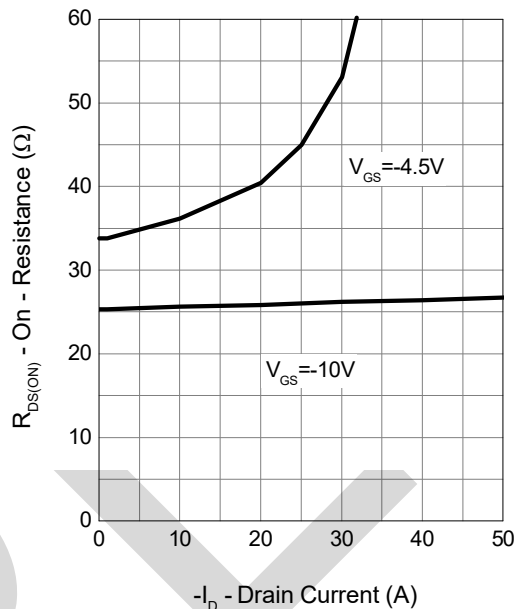


P Channel Typical Operating Characteristics (Cont.)

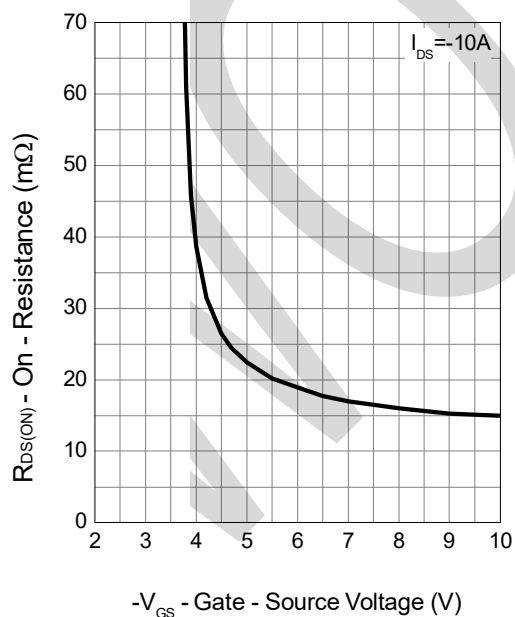
Output Characteristics



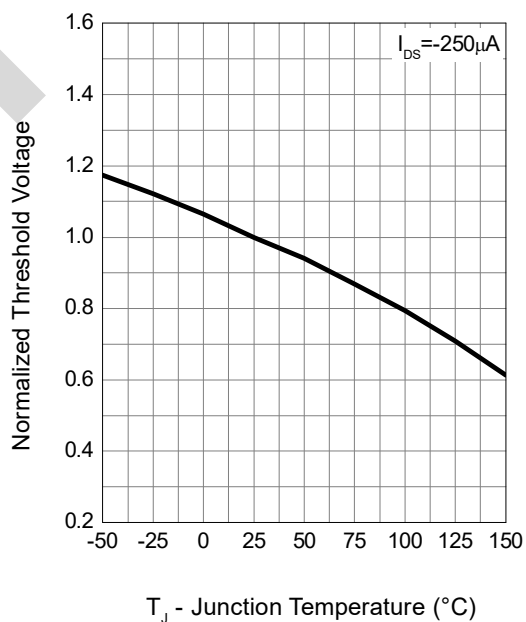
Drain-Source On Resistance



Transfer Characteristics

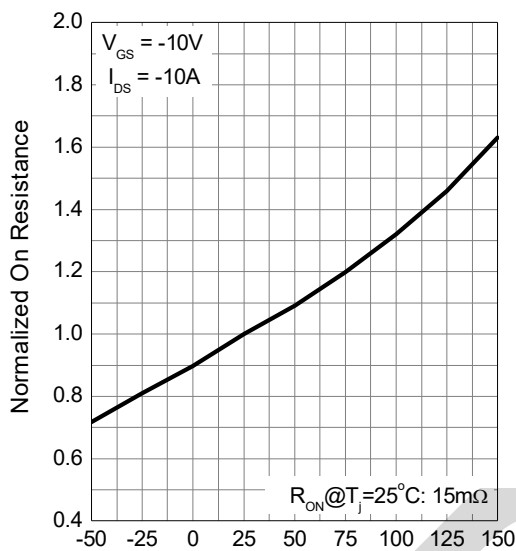


Gate Threshold Voltage



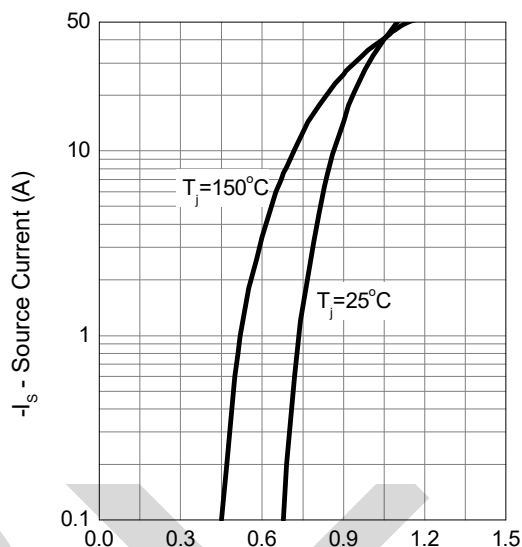
P Channel Typical Operating Characteristics (Cont.)

Drain-Source On Resistance



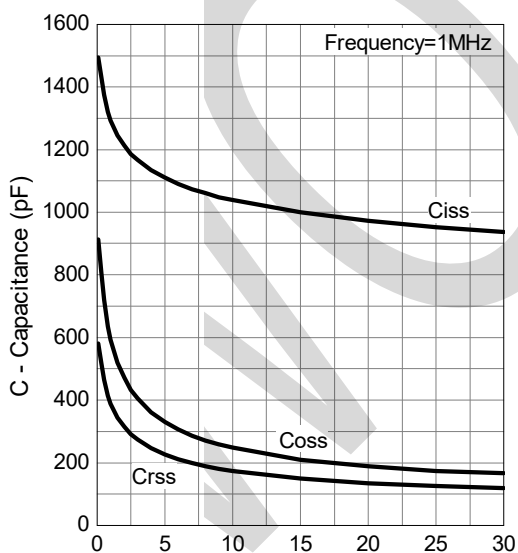
T_J - Junction Temperature ($^{\circ}\text{C}$)

Source-Drain Diode Forward



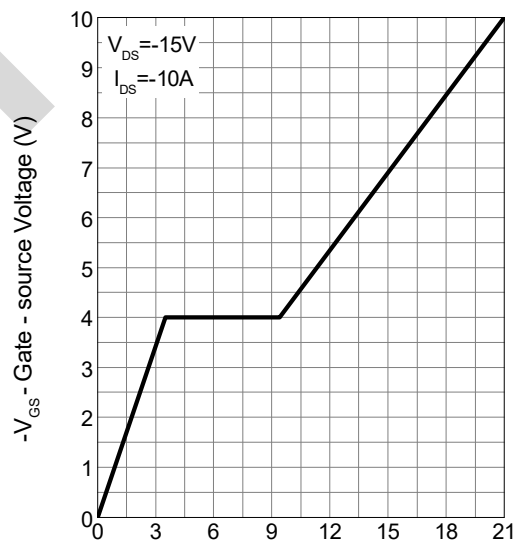
$-V_{SD}$ - Source - Drain Voltage (V)

Capacitance



$-V_{DS}$ - Drain - Source Voltage (V)

Gate Charge



Q_G - Gate Charge (nC)

PACKAGE OUTLINE DIMENSIONS

Note:unit mm

PDFN5X6

